Double Sided Probing Solutions

- Double Sided Probing Systems (DSP)
    - Stimulate from the topside and detect from the backside
    - Stimulate from the backside and detect from the topside
    - Simultaneously probe from both sides
- Family – Manual, Semiautomatic Fully Automatic
- MEMS, Optoelectronics, Failure Analysis
- Topside and bottom side platens with downward and upward looking optics and imaging systems
- Thermal Systems – 2 types – Chuck & Thermal Wand
    - Standard Chucks: -60 C to 300 C, Thermal Wand: -20 C to 225 C
- Customized Chucks and Carrier Plates for die, substrates, partial wafers and whole wafers to 300 mm
- Integrating Spheres or Fibers (single or multi-mode)
- Dark Boxes or Localized Environmental Chambers (LEC)
- Manipulators – manual, programmable and hexapods
- Non-Contact Height Measurement Sensors
- Probe Tips, Probe Cards, Multi-Contact DC & RF Wedges
- Integrated Solutions
- Modular PS4L Hardware & Software Architecture

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